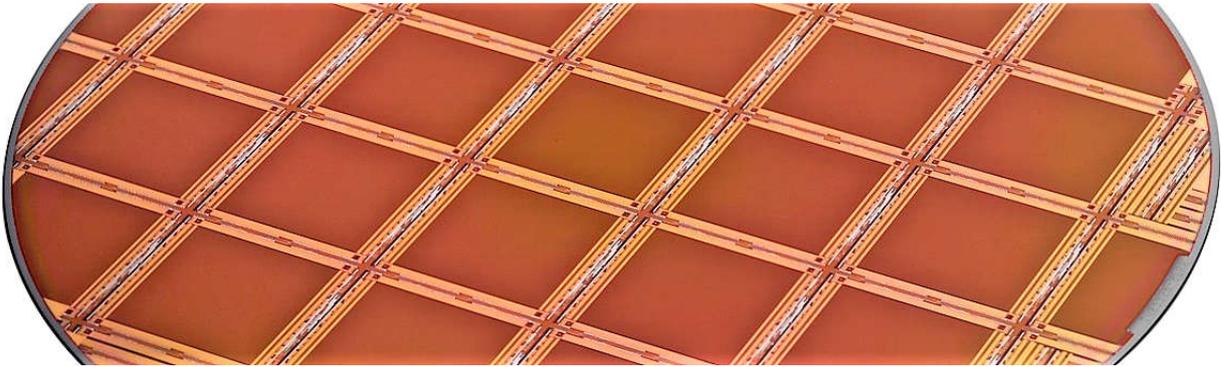


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Custom chip package design engineer



About Caeleste

Caeleste is a proud group of engineers, scientists & enthusiasts who create innovative CMOS image sensor solutions. We go the extra mile to create unique & beyond state-of-the-art solutions that allow our customers to differentiate in their field of expertise. From within our Belgian office, we collaborate with world-class multi-national companies that shape the market in space, scientific, medical, industrial and life science applications. Thanks to the in-house expertise on high-speed, sub-electron noise, ultra-high dynamic range and extreme radiation-hard designs, Caeleste ensures an end-to-end quality focus on the entire product flow. At Caeleste, having fun goes hand-in-hand with our pride. By becoming a part of Caeleste, you will be able to experience the direct impact of your ideas and actions, regardless of your role or seniority.

Custom chip package design engineer

To strengthen our system and test team we are looking for an engineer with experience in the design of custom ceramic, metal, and chip-on-board packages for image sensors. Your designs will be the essential interface between novel prototypes and products, and complex, high-speed analog & digital data acquisition systems. You organize sensor assembly to final encapsulated image sensors. These packages may be used anywhere from the lab to outer space. Next to package design you will also work on the design of PCB's used to validate and characterize novel CMOS image sensors. You will work in close collaboration with circuit board engineers, chip design engineers, and project managers and will interact with and manage external suppliers and service providers.

Although the prime focus is package & PCB design and supplier interaction, your thorough upfront analysis, documentation and first-time-right approach are critical for a quality focused collaboration in a team of experts that depend on your contributions in a project driven organization. You have the opportunity to grow according to your capabilities and aspirations. We foster experience, but also welcome junior engineers with great potential.

Job specific requirements:

Master of science in Electro-Mechanical Engineering, Mechanical Engineering, Electronics or equivalent by experience.

Experience with:

- Chip packaging: types, design methodology, best practices.
- Mechanical design and mechanics of materials.
- 3D CAD, mechanical drawings, geometric dimensioning and tolerancing.
- Finite element analysis, particularly: dynamic (modal), and thermal analysis.
- Electronic board design, bring-up and debug.
- Thorough understanding of PCB & packaging technology and materials.

Fast learner of theoretical and hands-on electronic design.

Creative, an analytical mindset and pragmatic problem-solving skills.

Excellent communication skills in English writing, presenting and customer interaction.

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Accountable & committed team player.

Additional skills that are of interest:

Experience with Altium designer or Inventor are a plus.
Experience with materials at cryogenic temperatures.
Experience with joining & sealing processes and hermeticity.
Experience with Autodesk Inventor and/or Altium designer.
Understanding of CMOS technology and mixed-signal analog/digital electronics.
Working language is English, any other language is a plus.

We offer:

A competitive compensation & benefits package
A competitive & international context of world-leading companies
A technological playground within a mixed-skilled, multi-cultural team of experts
A continuous focus on learning at Caeleste University
A flexible & pragmatic environment with attention to teamwork and work-life balance

For all your questions, please contact Ewa Burzynska or jobs@caeleste.be